

METHOD OF FORMING HSQFN TYPE PACKAGE

Abstract of the Disclosure

A method of forming a HSQFN (High Stand-off Quad Flat Non-leaded) package comprises providing a leadframe with bonding pads and die pads for receiving a die. Then, the die is attached on the die pad and bonding wires are connected between the bonding pads and the die for electrical connection. Molding process is used to encompass the die by compound from a first surface of the leadframe. Then, backside etching is used to etch the leadframe from a second surface of the leadframe to expose a lower surface of the compound, thereby separating the bonding pads and the die pads. A sigulation is applied to separate each individual package by cutting the leadframe and the compound.